PNA4S54F

Photodiode with amplifier functions

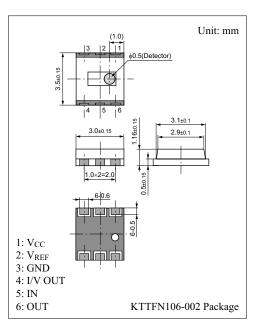
For optical control systems

Features

- Small package, × 52 speed
- Reflow soldering possible

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|------------|------|--|
| Operating supply voltage | V _{CC} | 6 | V | |
| Power dissipation | P _D | 250 | mW | |
| Operating ambient temperature | T _{opr} | -20 to +70 | °C | |
| Storage temperature | T _{stg} | -40 to +85 | °C | |



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$, $V_{CC} = 5.0 \text{ V}$, $V_{REF} = 2.5 \text{ V}$, $R_L = 10 \text{ k}\Omega$, $C_L = 10 \text{ pF}$, $V_R = 200 \Omega$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-----------------------------|----------------------|---|------|------|------|------|
| Operating supply voltage *4 | V _{CC} | | 4.5 | 5.0 | 5.5 | V |
| Output voltage *1 | Vo | $PI = 50 \ \mu W, \ \lambda = 780 \ nm$ | -95 | -140 | -190 | mV |
| Output offset voltage *2 | V _{OFF} | | -10 | 0 | 10 | mV |
| Output maximum voltage | V _{OM} | V _{REF} standard | -2.0 | -2.2 | | V |
| Reference voltage *4 | V _{REF} | | 2.0 | 2.5 | 2.75 | V |
| Supply current | I _{CC} | No signal condition | | 1.5 | 20 | mA |
| Cutoff frequency *3 | f _{C(-3dB)} | Gurantee item on design | | 80 | | MHz |
| Rise time | t _r | $V_{\rm O} = 1$ V, 10% to 90% | | 5 | | ns |
| Fall time | t _f | | | | | |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

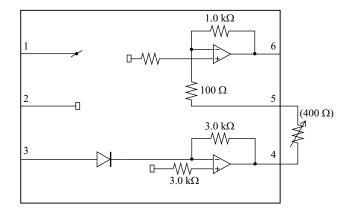
2. *1: Standard voltage level; V_{REF} (Exclude output offset voltage)

*2: Standard voltage level; V_{REF}

*3: 20 log (V₀ (f_C MHz)/V₀(1 MHz)) = -3

*4: $(V_{CC} - V_{REF})$ Voltage: more than 2.0 V

Block Diagram



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